

2SK3418

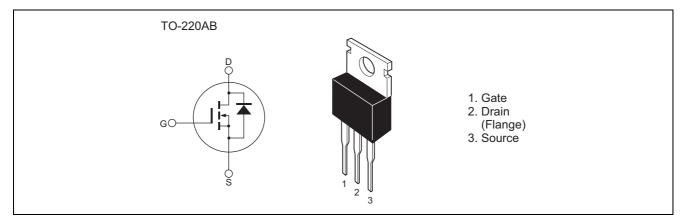
Silicon N Channel MOS FET High Speed Power Switching

> REJ03G0407-0200 (Previous ADE-208-941 (Z)) Rev.2.00 Sep.10.2004

Features

- Low on-resistance $R_{DS(on)} = 4.3 \text{ m}\Omega \text{ typ.}$
- Capable of 4 V gate drive
- High speed switching

Outline



Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	60	V
Gate to source voltage	V _{GSS}	±20	V
Drain current	ID	85	A
Drain peak current	I _D (pulse) ^{Note1}	340	A
Body-drain diode reverse drain current	I _{DR}	85	A
Avalanche current	I _{AP} ^{Note3}	60	A
Avalanche energy	E _{AR} ^{Note3}	308	mJ
Channel dissipation	Pch ^{Note2}	110	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	– 55 to +150	°C

Notes: 1. $PW \le 10\mu s$, duty cycle $\le 1\%$

2. Value at Tc = 25°C

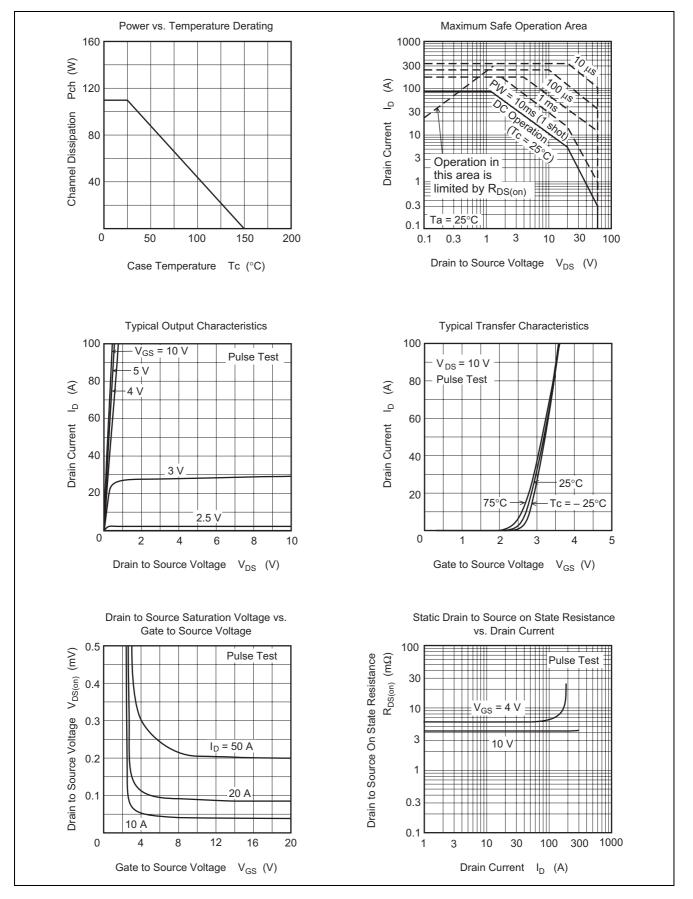
3. Value at Tch = 25°C, Rg \ge 50 Ω

Electrical Characteristics

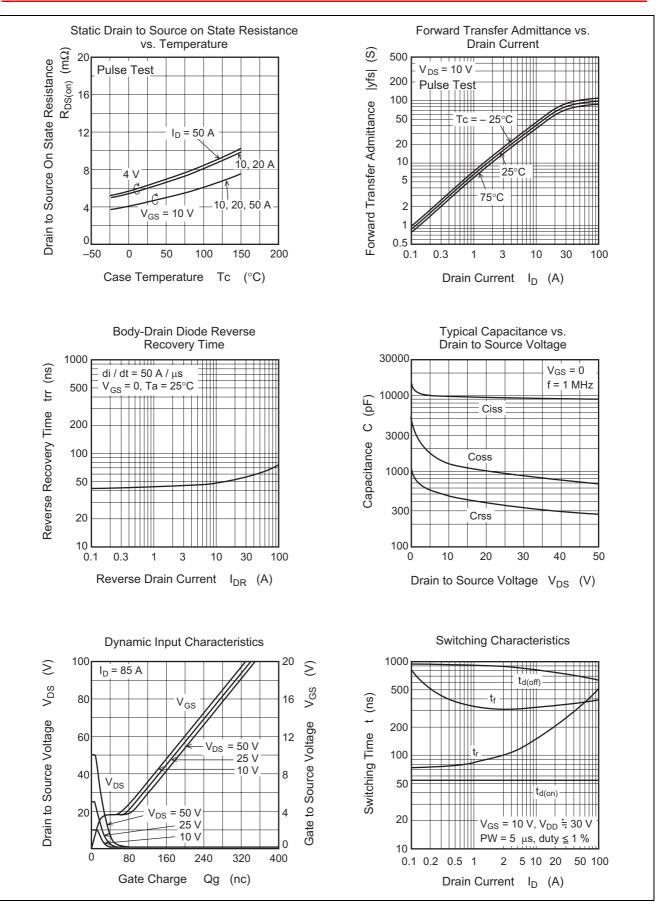
						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	V _{(BR)DSS}	60	—	—	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Zero gate voltage drain current	I _{DSS}	_	—	10	μΑ	$V_{DS} = 60 V, V_{GS} = 0$
Gate to source leak current	I _{GSS}		—	±0.1	μΑ	$V_{GS} = \pm 20 \text{ V}, \text{ V}_{DS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	1.0	—	2.5	V	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}^{\text{Note1}}$
Forward transfer admittance	y _{fs}	55	90	—	S	$I_D = 45 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note1}}$
Static drain to source on state	R _{DS(on)}		4.3	5.5	mΩ	$I_D = 45 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note1}}$
resistance	R _{DS(on)}		6.0	9.0	mΩ	$I_D = 45 \text{ A}, V_{GS}=4 \text{ V}^{\text{Note1}}$
Input capacitance	Ciss		9770	—	pF	V _{DS} = 10 V
Output capacitance	Coss		1340	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss		470	—	pF	f = 1 MHz
Total gate charge	Qg		180	—	nC	V _{DD} = 50 V
Gate to source charge	Qgs		32	—	nC	V _{GS} = 10 V
Gate to drain charge	Qgd	_	36	_	nC	I _D = 85 A
Turn-on delay time	t _{d(on)}	_	53	—	ns	V _{GS} = 10 V
Rise time	tr		320	—	ns	I _D = 45 A
Turn-off delay time	t _{d(off)}		700	—	ns	$R_L = 0.67 \Omega$
Fall time	t _f		380	—	ns	
Body-drain diode forward voltage	V _{DF}	_	1.0		V	$I_F = 85 \text{ A}, V_{GS} = 0$
Body-drain diode reverse recovery time	t _{rr}	_	70	_	ns	$I_F = 85 \text{ A}, V_{GS} = 0$ diF / dt = 50 A / μ s
Noto: 1 Pulso tost						$\mu = 50 \text{ A}/\mu \text{s}$

Note: 1. Pulse test

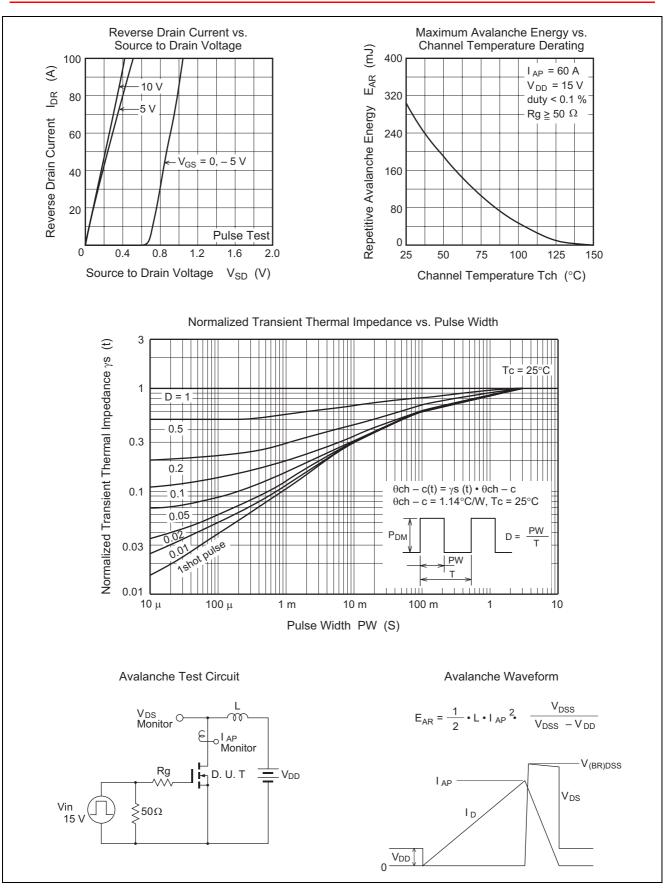
Main Characteristics



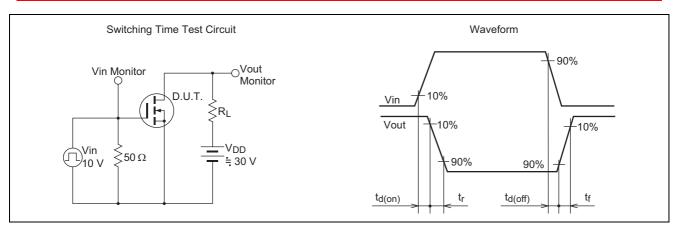




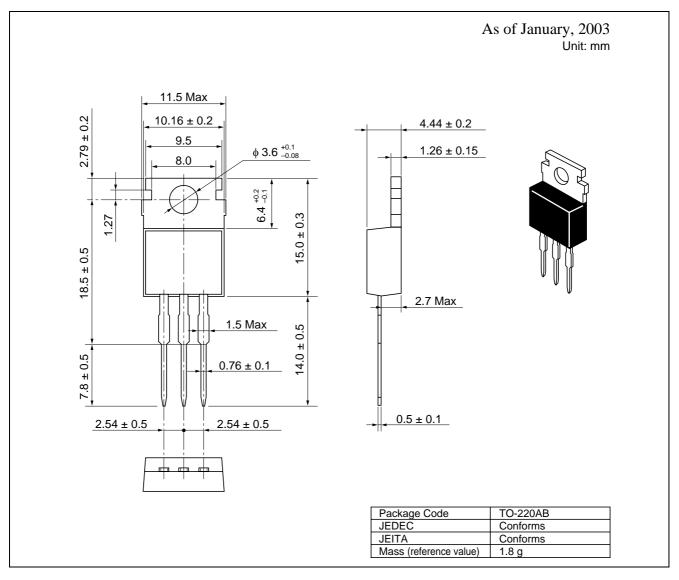
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Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container	
2SK3418-E	50 pcs	sack	

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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